

**AMENDMENTS TO THE SPECIFICATION**

Please amend the paragraph starting at page 9, line 28 as follows:

According to an alternative embodiment of the invention, a thin layer of metal 91 (FIG. 8) is located on the back side of the semiconductor device 12. A layer of adhesive 92 is located between the thin layer of metal 91 and a thicker metal layer 90. The adhesive 92 may extend through the thin layer of metal ~~adhesive~~ 91 to provide adherence to the semiconductor device 12. The thickness of the thin layer of metal 91 ~~layer~~ may be about 0.00254 millimeters. The product shown in FIG. 8 otherwise may be the same as the one shown in FIG. 7.

OK, to enter.  
CAL